

07-22-1999

Docket No.: FP-3408US

U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Office

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09/352293
07/12/99

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copies.

1. Name of conveying party(ies):

Shinji Ogawa

2. Name and address of receiving party(ies):

Name: Sumitomo Wiring Systems, Ltd.

Address: 1-14, Nishisuehiro-cho

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other

City: Yokkaichi-City

State/Prov.: _____

Country: Japan

ZIP: Mie 510-8503

Execution Date: July 9, 1999

Additional name(s) & address(es)

☐ Yes ☒ No

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is: July 9, 1999

Patent Application No.

Filing date

B. Patent No.(s)

09/352293

Additional numbers

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Gerald E. Hespos

Registration No. 30,066

Address: 274 Madison Avenue - Suite 1703

City: New York

State/Prov.: NY

Country: U.S.A.

ZIP: 10016

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account

☐ Authorized to be charged to deposit account

8. Deposit account number:

03-1030

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Gerald E. Hespos

Name of Person Signing

Gerald E. Hespos
Signature

July 12, 1999

Date

Total number of pages including cover sheet, attachments, and

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No. 1281 P. 4

Atty. Ref.: FP-3408US

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned by the Assignee, Sumitomo Wiring Systems, Ltd., a corporation organized under the laws of Japan, located at 1-14, Nishisuehiro-cho, Yokkaichi-City, Mie, 510-8503, Japan, receipt whereof is hereby acknowledged, the undersigned by these presents hereby sells, assigns, transfers and sets over unto the said assignee the entire right, title and interest in and to the invention or improvement entitled "A MOLDED COIL A METHOD AND A MOLD FOR PRODUCING THE SAME", said invention being fully described and/or claimed in the application for Letters Patent of the United States of America, executed this date, in and for the United States and all foreign countries, the same to be held and enjoyed by said assignee, its successors, assigns or other legal representatives, to the full ends of the terms for which all Letters Patent therefor may be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

And Said Assignee Is Hereby Authorized to make application for and to receive Letters Patent for said invention in any of said countries at its election.

And By This Covenant The Undersigned will execute or procure any further necessary assurance of title to said invention and Letters Patent; and at any time, upon the request and at the expense of said assignee, will execute and deliver any and all papers that may be necessary or desirable to perfect the title to said invention or any Letters Patents which may be granted therefor in said Assignee, its successors, assigns or other legal representatives, and, upon the request and at the expense of said assignee, will execute any additional or divisional applications for patents for said invention, or any part or parts thereof, and for the reissue of any Letters Patents to be granted therefor, and will make all rightful oaths and do all lawful acts requisite for procuring the same or for aiding therein, without further compensation, but at the expense of said assignee, its successors, assigns or other legal representatives.

And The Commissioner Of Patents Is Hereby Authorized And Requested to issue any and all Letters Patent of the United States for said invention, to said assignee.

Signed and sealed this 9 day of July, 1999.

Shinji Ogawa L.S.
Shinji Ogawa